

Title (en)  
TITANIUM COPPER FOR ELECTRONIC COMPONENTS

Title (de)  
TITANKUPFER FÜR ELEKTRONISCHE KOMPONENTEN

Title (fr)  
TITANE-CUIVRE POUR COMPOSANTS ÉLECTRONIQUES

Publication  
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Application  
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Abstract (en)  
[origin: EP3460082A2] The present invention is intended to improve bending workability of titanium copper for electronic components, and to provide a titanium copper for electronic components, which has excellent bending workability even when subjected to beating process, and to provide a method for manufacturing the same. One embodiment of the present invention is a titanium copper, comprising 2.0 to 4.5 mass% of Ti, and at least one element selected from the group consisting of Fe, Co, Ni, Cr, Zn, Zr, P, B, Mo, V, Nb, Mn, Mg, and Si in total of 0 to 0.5 mass% as a third element(s), and the rest consisting of copper and inevitable impurities, wherein a work-hardening exponent is 0.05 to 0.25, and an X-ray diffraction integrated intensity  $I_{\{200\}}$  from the  $\{200\}$  crystal face on the surface of the titanium copper and an X-ray diffraction integrated intensity  $I_0$  of a pure copper standard powder satisfy the following relation:  $0.15 \leq I_{\{200\}} / I_0 \leq 0.70$ .

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